

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4114885	substrate board pcb ((printed circuit wiring) adj3 board) carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:32
L2	853575	(die chip ic (integrated adj circuit) semiconductor dice) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:37
L3	249791	(electrode pad terminal) with (projection projected projecting interweave interweaved interweaving integration integrated intergrating interlock interlocking interlocked interdigitated interdigitating interdigitation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:38
L4	1047843	3 sane 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:36
L5	33408	3 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:36
L6	707220	(die chip ic (integrated adj circuit) semiconductor dice) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:37
L7	23935	6 with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:38

L8	2887	(electrode pad terminal) with (projection projected protrude protruding protruded projecting) with (interweave interweaved interweaving integration integrated intergrating interlock interlocking interlocked interdigitated interdigitating interdigitation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:39
L9	533	6 with 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/08 07:39